

TDS



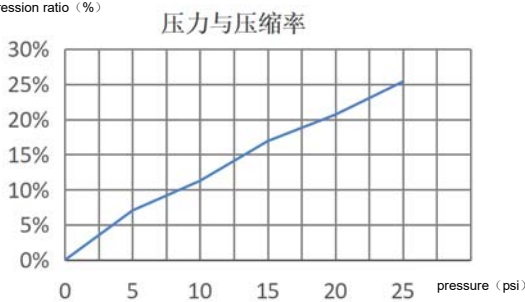
K-HC 800E is a universal thermal gasket that can meet the heat dissipation requirements without special hardness requirements, and its softness can meet most pressure assembly requirements, showing small thermal resistance, while eliminating air between components and circuit boards, and fully filling all kinds of rough surfaces. The product comes with its own stickiness. The default is no substrate structure, and can be customized to have a substrate structure, such as backsilicon tape /3M glue/glass fiber and other processes to meet special requirements.

peculiarity

- Heat conductivity =8.0W/mk
- High adhesion, ultra-low hardness, suitable for low tightening pressure
- Fire protection meets V0, environmental protection meets ROHS requirements
- Resistance to puncturing, shearing and tearing

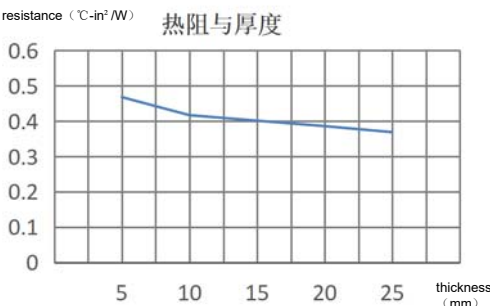
Compression graph

compression ratio (%)



Thermal resistance diagram

thermal resistance (°C-in²/W)



Symbol properties		
properties of products	test value	test method
colour	light grey	Visual
Thickness rang(mm)	1.0 - 12	ASTM D374
density(g/cm ³)	3.5±0.2	ASTM D792
hardness (Shore C)	30-50(±5)	ASTM D2240
break down voltage (KV/AC)	≥6	ASTM D149
dielectric constant (1.2MHz)	≥5.5	ASTM D150
mass resistivity(Ω.cm)	≥1.0*10 ¹³	ASTM D257
Continuous use Temp(°C)	-40 ~ 200	EN344
weight loss(%)	≤1	@180°C 4H
fire rating	V0	UL 94
heat conductivity coefficient (W/m-K)	≥8.0	ASTM D5470

Thickness tolerance ≤ 10% of product thickness

typical application

communications industry

Computer and peripheral power converters

Between semiconductor or magnetic body and heat sink

An area where a frame, chassis, or other heat transmitter requires heat transfer

OfferSpecification: sheet, die cutting

standard thickness mm: 1.0, 1.5, 2.0, 2.5, 3.0 Other thicknesses need to be customized;

Parallel Deviation mm: 200*400, Other sizes need to be customized;

storage condition: temperature≤40°C , humidity≤70%RH;

Note: Please refer to the MSDS report for the safety data of the product. The data in this paper are obtained under laboratory conditions. Due to the differences in the conditions of use, users need to refer to these data and conditions of use for analysis and testing. The company does not guarantee the sale of this product and the use of the company's products under specific conditions of the problem, does not assume any direct, indirect or accidental loss liability. Users can contact the technical service department across the company if they encounter any problems in the use process.